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ABSTRACT

A sensor package structure is provided. The sensor package structure includes a substrate, a sensor chip disposed on the substrate, a light-curing layer disposed on the substrate and surrounding the sensor chip, a light-permeable layer disposed on the light-curing layer, and a shielding layer that is ring-shaped and that is disposed on the light-permeable layer. And inner surface of the light-permeable layer, the light-curing layer, and the substrate jointly define an enclosed space that accommodates the sensor chip. A first projection area defined by orthogonally projecting the shielding layer onto the inner surface does not overlap the assembling region. A second projection area defined by orthogonally projecting the sensing region onto the inner surface along the predetermined direction does not overlap the first projection area and is located inside of the first projection area.

